

**Date:** Apr 2013  
**Rev:** V  
**No. of Components:** Two  
**Mix Ratio by Weight:** 10:1  
**Specific Gravity:** Part A: 3.10 Part B: 0.96  
**Pot Life:** 6 Hours  
**Shelf Life:** One year at room temperature

**Recommended Cure:** 150°C / 1 Hour

Minimum Alternative Cure(s):	
<i>may not achieve performance properties below</i>	
150°C	15 Minutes
80°C	3 Hours
23°C	3 Days

*NOTE: Container(s) should be kept closed when not in use. Filled systems should be stirred thoroughly before mixing and prior to use.*

**Product Description:** EPO-TEK<sup>®</sup> E4110-LV is a two component, silver-filled epoxy used in electronic and circuit assembly applications in semiconductor and optical industries. A low viscosity version of EPO-TEK<sup>®</sup> E4110.

**Typical Properties:**

*To be used as a guide only, not as a specification. Different batches, conditions & applications yield differing results.  
 Cure condition: 150°C / 1 Hour \* denotes test on lot acceptance basis Data below is not guaranteed.*

**PHYSICAL PROPERTIES:**

* <b>Color (before cure):</b>	Part A: Silver	Part B: Clear /Colorless
* <b>Consistency</b>	Smooth flowing paste	
* <b>Viscosity (23°C): @ 100 rpm</b>	350-850 cPs	
<b>Thixotropic Index:</b>	1.9	
* <b>Glass Transition Temp:</b>	≥ 40 °C (Dynamic Cure:20-200°C/ISO 25 Min; Ramp -10-200°C @ 20°C/Min)	
<b>Coefficient of Thermal Expansion (CTE):</b>		
<b>Below Tg:</b>	50 x 10 <sup>-6</sup> in/in°C	
<b>Above Tg:</b>	283 x 10 <sup>-6</sup> in/in°C	
<b>Shore D Hardness:</b>	60	
<b>Lap Shear @ 23°C:</b>	1,080	
<b>Die Shear @ 23°C:</b>	≥ 5 Kg	1,700 psi
<b>Degradation Temp:</b>	365 °C	
<b>Weight Loss:</b>		
@ 200°C	0.33 %	
@ 250°C	0.65 %	
@ 300°C	1.19 %	
<b>OperatingTemp:</b>		
<b>Continuous:</b>	- 55°C to 150°C	
<b>Intermittent:</b>	- 55°C to 250°C	
<b>Storage Modulus:</b>	788,340 psi	
<b>Ion Content:</b>		
<b>Cl:</b>	332 ppm	NA <sup>+</sup> : 0 ppm
<b>NH<sub>4</sub><sup>+</sup>:</b>	27 ppm	K <sup>+</sup> : 0 ppm
* <b>Particle Size:</b>	≤ 45 microns	

**ELECTRICAL AND THERMAL PROPERTIES:**

<b>Thermal Conductivity:</b>	1.78 W/mK
* <b>Volume Resistivity @ 23°C:</b>	≤ 0.0005 Ohm-cm
<b>Volume Resistivity @ 23°C (25°C/40-60%RH/3Day cure):</b>	≤ 0.007 Ohm-cm

Epoxyes and Adhesives for Demanding Applications™

**This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.**

**EPO-TEK<sup>®</sup> E4110-LV Advantages & Suggested Application Notes:**

- Very low viscosity, silver-filled epoxy which can be applied by hand, brushing, roll coating, tooth-picking or stamping, or spraying.
- After cure, it has a shiny, almost metallic looking finish. This can be used to repair surface imperfections in metal coating applications such as electroplating or sputtering processes.
- Suggested applications:
  - ◇ Electronics - filling vias at the PCB level for top-to-bottom connections; EMI & Rf shielding applications.
  - ◇ Hybrids - electrically conductive potting for radar systems. The potting can be self-leveling, trapping no voids, and non-cracking with performance.
  - ◇ Optics - die-attaching LED's by the stamping process, or pin-transferring applications.
- Passes NASA low outgassing standard ASTM E595 with proper cure - <http://outgassing.nasa.gov/>

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